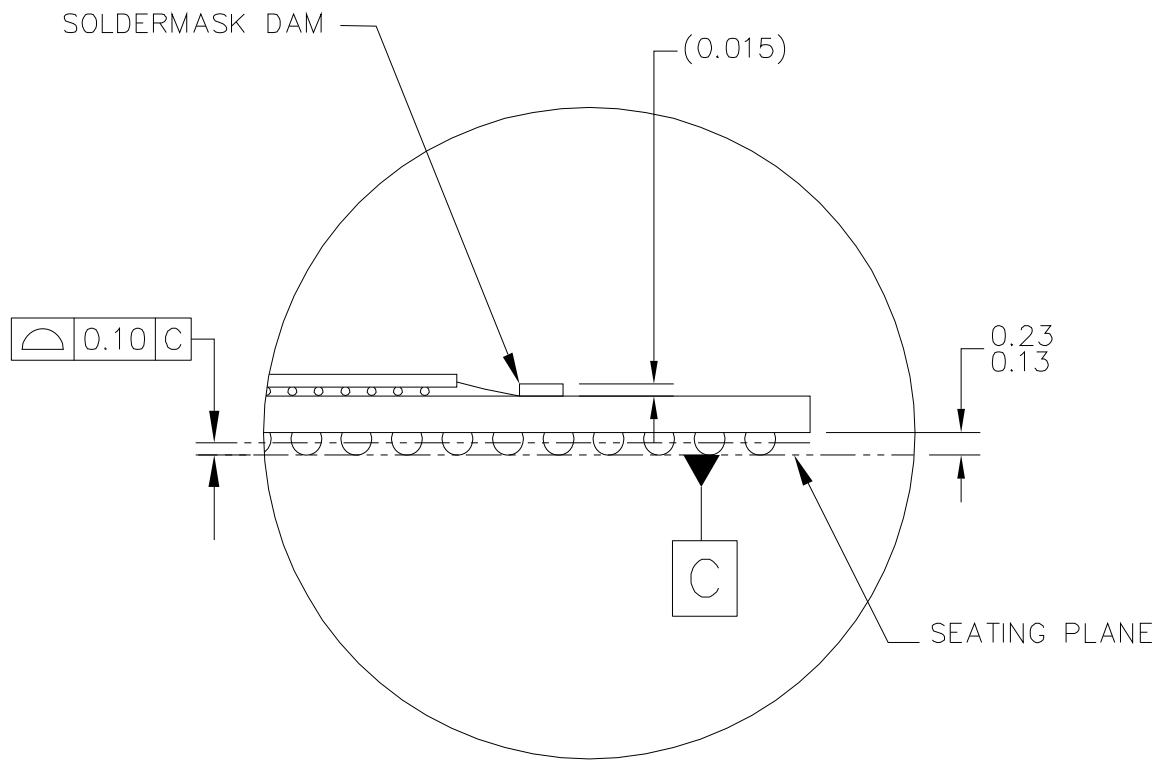


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TITLE: FC-PBGA, POP, FINE PITCH, 520 I/O, 12 X 12 PKG, 0.4 MM PITCH (MAP)	DOCUMENT NO: 98ASA00298D	REV: 0	
	CASE NUMBER: 2177-01	19 JAN 2011	
	STANDARD: NON-JEDEC		



DETAIL A
ROTATED 90°

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. REFLOW BALL DIAMETER.

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